ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS (NOUSTRIES®) international and Par	PC, Bannockl	burn, Illinois. A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declarat he declaration e	on of the su	ibstances v s all lower	within the manufactu level materials for v	arer listed i which the n	tem. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information				· ·							-		
Company name* Company unique ID					1	Unique ID Authority			Response Date*				
nsemi						2024-09-20							
Contact Name Title - Contact			t]	Phone - Contact* Email - Contact*							
Product-Env-Stewards Product Env			ro Compliance		NA			Produc	Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Represen			entative	Phone - Representative* Email - Representative*									
Product-Env-Stewards Product			ro Compliance		NA Product-Env-Stewards@onsemi.com				m				
Requester Item Number Mfr Item		Number Mfr Item Name			Effective Date	Version	M	Manufacturing Site		Weight*	UOM	Unit Type	
		0132AT6G00XPE 1MP 1/3 CIS SO AA-DRBR				2024-09-20	TWU			198.94	mg	Each	
Ianufacturing Proccess Informa	tion												
Terminal Plating / Grid Array Material Terminal Base Alloy J-ST			J-STD-020 MSL	Rating	Peak Proc	ess Body To	emperature	e Max Time at Peal	k Temperat	ure Num	ber of Reflow Cyc	les	
SnAgCu CU Alloy 3			3		260		C	30	secon	ids 3			
omments													
FTENTION: MSL 3 Rated item require	s Bake and L	Dry Pack (after	electrical test)										
or more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	46.746	mg		Misc.	proprietary data		0.1776	mg
			Supplier	Silicon (Si)	7440-21-3		46.1056	mg
			Supplier	Aluminum (Al)	7429-90-5		0.4628	mg
Die Attach	2.852	mg		Bismaleimide Monomer	proprietary data		1.098	mg
			Supplier	POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE	56641-05-5		0.0143	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.2852	mg
			Supplier	Bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3		0.0143	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.2852	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.2852	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0143	mg
			Supplier	Other Additive Agents	Proprietary Data		0.5704	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.2852	mg
Imaging Lens	29.239	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5388	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5388	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.1541	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5388	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5388	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5388	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.3907	mg
Lid Attach	1.459	mg	Supplier	2,2-Bis(glycidyloxyphenyl)propane polymer	25085-99-8		0.3647	mg
			Supplier	3,4-EPOXYCYCLOHEXYLMETHYL	2386-87-0		1.0578	mg
			Supplier	Misc.	Proprietary Data		0.0365	mg
Mold Compound	43.49	mg		Epoxy resin	proprietary data		10.7855	mg
			Supplier	Other Additive Agents	Proprietary Data		1.3917	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.349	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.6591	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.3047	mg
Solder Ball	35.868	mg	Supplier	Silver (Ag)	7440-22-4		1.076	mg

			Supplier	Tin (Sn)	7440-31-5	34.6126	mg
			Supplier	Copper (Cu)	7440-50-8	0.1793	mg
Solder Mask	4.22	mg		Epoxy resin	proprietary data	0.5064	mg
			Supplier	Acrylate	Proprietary Data	1.612	mg
			Supplier	Talc	14807-96-6	0.1139	mg
			Supplier	Miscellaneous	Trade Secret	0.1561	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	1.8315	mg
Substrate Copper Foil	3.09	mg	Supplier	Copper (Cu)	7440-50-8	3.09	mg
Substrate - Core Material	16.24	mg		Epoxy resin	proprietary data	3.5192	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	12.7208	mg
Substrate Plating-Au	0.29	mg	Supplier	Gold (Au)	7440-57-5	0.29	mg
Substrate Plating-Cu	14.49	mg	Supplier	Copper (Cu)	7440-50-8	14.49	mg
Substrate Plating-Ni	0.67	mg	В	Nickel (Ni)	7440-02-0	0.67	mg
Wire Bond - Au	0.286	mg	Supplier	Gold (Au)	7440-57-5	0.286	mg